# MSKSEMI 美森科



**ESD** 





TSS



MOV



GDT



PIFD

## **ESDA05CP**

## **Product specification**





## **FEATURES**

Capacitance: 15pF(typ.) Reverse Working Voltage: 5V IEC 61000-4-2 (ESD Air): ±25KV

> IEC 61000-4-2 (ESD Contact): ±25KV IEC 61000-4-5 (Lightning 8/20µs): 8A

## **MACHANICAL DATA**

DFN1006-2L package

Flammability Rating: UL 94V-0

Packaging: Tape and Reel

High temperature solderin guaranted:260 C/10 s

Reel size: 7 inch

#### **APPLICATIONS**

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA

## **Reference News**

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		C*
DFN1006-2L		



## **ABSOLUTE MAXIMUM RATING**

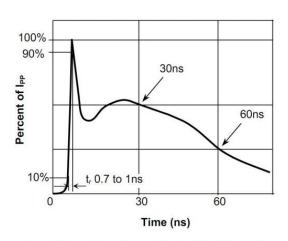
Symbol	Parameter	Conditions	Min	Max	Unit
	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	±25	V
VESD		IEC 61000-4-2; Air Discharge	-	±25	V
PPP	Peak Pulse Power	tP = 8/20 μs	-	80	W
IPPM	Rated Peak Pulse Current	tP = 8/20 μs	-	8	Α
TA	Ambient Temperature Range	-	-55	125	$^{\circ}\!\mathbb{C}$
Tstg	Storage Temperature Range	-	-55	150	$^{\circ}\!$

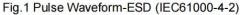
## **ELECTRICAL CHARACTERISTICS (Tamb=25℃)**

Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
VRWM	Reverse Working Voltage	TA = 25 °C	-	-	5.0	V
VBR	Breakdown Voltage	IR = 1mA; TA = 25 °C	5.6	6.5	8.4	V
IR	Reverse Leakage Current	VRWM = 5V; TA = 25 °C	-	-	0.1	Α
VC	Clamping Voltage	IPP=1A, tP =8/20μs	-	-	6	V
		IPP=8A, tP =8/20μs	-	-	10	V
CJ	Junction Capacitance	VR = 0V, f = 1 MHz	-	15	18	F



## **ELECTRICAL CHARACTERISTICS CURVE**





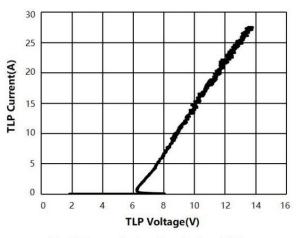


Fig.2 Transmission Line Pulse (TLP)

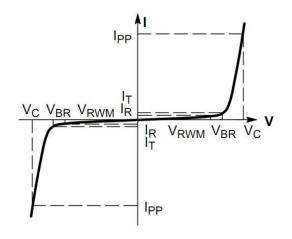


Fig.3 V-I Characteristics for Bidirectional Diode

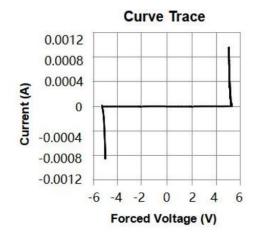


Fig.4 IV Curve

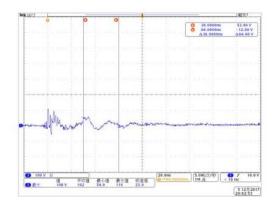


Fig.5 Clamping Voltage at IEC61000-4-2 +8kV Pulse Waveform

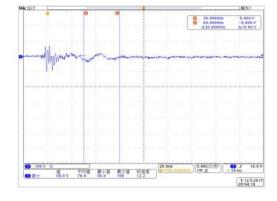
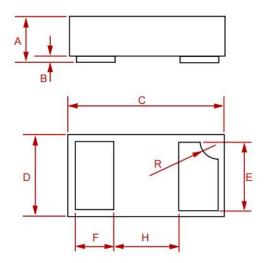


Fig.6 Clamping Voltage at IEC61000-4-2 -8kV Pulse Waveform

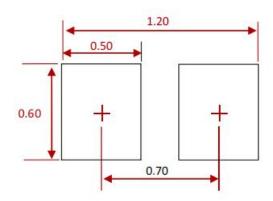


#### PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters		
Dim	MIN	MAX	MIN	MAX	
Α	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
Н	0.015Typ.		0.40	Тур.	
R	0.001	0.005	0.05	0. 15	

## **Suggested Pad Layout**



#### NOTES:

1.CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).

2.THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
ESDA05CP	DFN1006-L	10000



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